MBRS540T3G, NRVBS540T3G

Surface Mount Schottky Power Rectifier

The MBRS540T3 employs the Schottky Barrier principle in a large area metal-to-silicon power diode. State-of-the-art geometry features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency rectification, or as free wheeling and polarity protection diodes in surface mount applications where compact size and weight are critical to the system.

Features

- Small Compact Surface Mountable Package with J-Bend Leads
- Rectangular Package for Automated Handling
- Highly Stable Oxide Passivated Junction
- Excellent Ability to Withstand Reverse Avalanche Energy Transients
- Guard-Ring for Stress Protection
- NRVB Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable*
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Mechanical Characteristics

- Case: Epoxy, Molded, Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: 217 mg (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Polarity: Polarity Band on Plastic Body Indicates Cathode Lead
- ESD Rating:
 - Machine Model, C (> 400 V)
 - ◆ Human Body Model, 3B (> 8000 V)
- Device Meets MSL 1 Requirements



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SCHOTTKY BARRIER RECTIFIER 5.0 AMPERES, 40 VOLTS



SMC 2-LEAD CASE 403AC

MARKING DIAGRAM



B540	= Specific Device Code
А	= Assembly Location**
Y	= Year
WW	= Work Week
	= Pb-Free Package

(Note: Microdot may be in either location)

**The Assembly Location code (A) is front side optional. In cases where the Assembly Location is stamped in the package, the front side assembly code may be blank.

ORDERING INFORMATION

Device	Package	Shipping [†]
MBRS540T3G	SMC (Pb-Free)	2,500 / Tape & Reel
NRVBS540T3G*	SMC (Pb-Free)	2,500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	40	V
Average Rectified Forward Current (At Rated V_R , T_C = 105°C)	I _{F(AV)}	5	A
Peak Repetitive Forward Current (At Rated V_R , Square Wave, 20 KHz, $T_C = 80^{\circ}C$)	I _{FRM}	10	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I _{FSM}	190	A
Storage Temperature Range	Tstg	-65 to +150	°C
Operating Junction Temperature (Note 1)	TJ	-65 to +150	°C
Voltage Rate of Change (Rated V _R)	dv/dt	10,000	V/µs

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. 1. The heat generated must be less than the thermal conductivity from Junction–to–Ambient: $dP_D/dT_J < 1/R_{\theta JA}$.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance,			°C/W
Junction-to-Lead (Note 2) Thermal Resistance,	$R_{\theta JL}$	12	
Junction-to-Ambient (Note 2)	$R_{ heta JA}$	111	

2. Rating applies when surface mounted on the minimum pad size recommended.

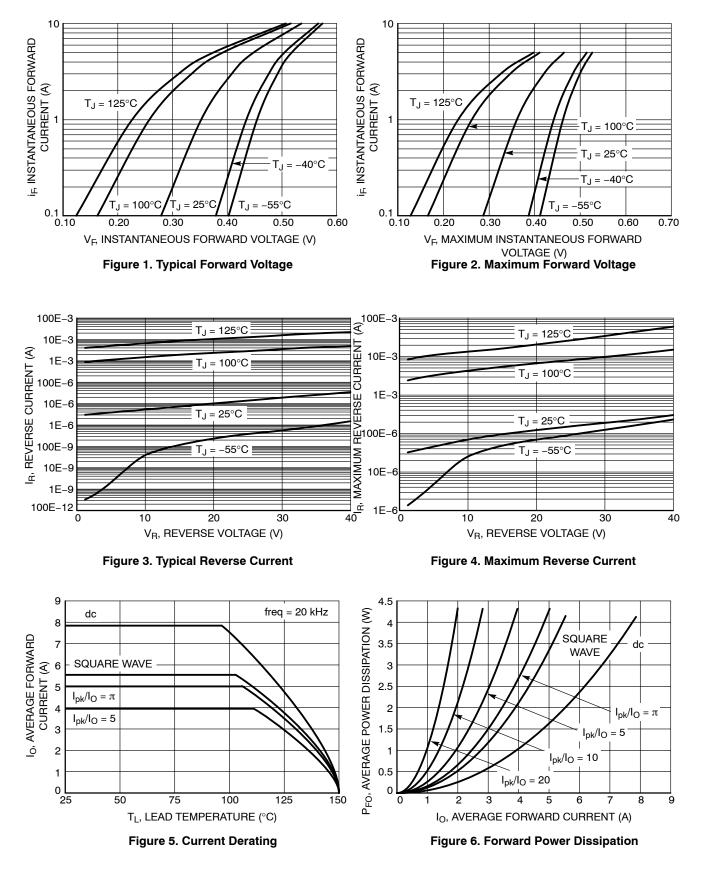
ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 3) ($i_F = 5.0 \text{ A}, T_C = 25^{\circ}\text{C}$)	V _F	0.50	V
Maximum Instantaneous Reverse Current (Note 3) (Rated dc Voltage, $T_C = 25^{\circ}C$) (Rated dc Voltage, $T_C = 100^{\circ}C$)	İR	0.3 15	mA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%.

NRVBS540T3G

TYPICAL CHARACTERISTICS



NRVBS540T3G

TYPICAL CHARACTERISTICS

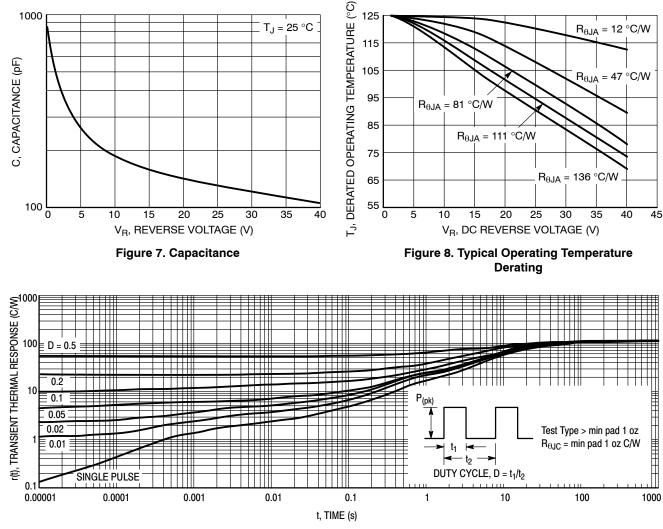
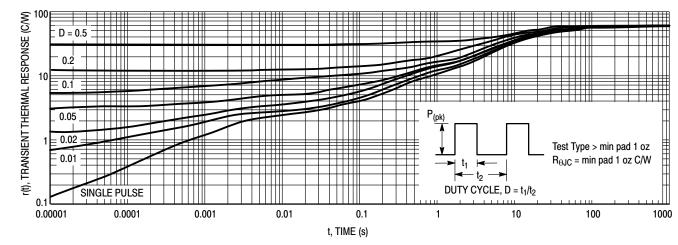


Figure 9. Thermal Response – MBRS540T3G, NRVBS540T3G on min pad



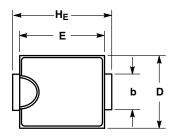


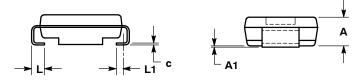
DATE 02 JUN 2017



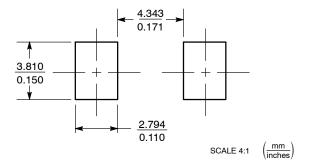
SMC CASE 403-03 **ISSUE F**







SOLDERING FOOTPRINT*

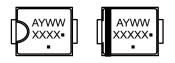


*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. D DIMENSION SHALL BE MEASURED WITHIN DIMENSION P. 4. 403-01 THRU -02 OBSOLETE, NEW STANDARD 403-03.

				INCLIFE			
	MILLIMETERS				INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	1.90	2.13	2.41	0.075	0.084	0.095	
A1	0.05	0.10	0.15	0.002	0.004	0.006	
b	2.92	3.00	3.07	0.115	0.118	0.121	
с	0.15	0.23	0.30	0.006	0.009	0.012	
D	5.59	5.84	6.10	0.220	0.230	0.240	
E	6.60	6.86	7.11	0.260	0.270	0.280	
HE	7.75	7.94	8.13	0.305	0.313	0.320	
L	0.76	1.02	1.27	0.030	0.040	0.050	
L1		0.51 REF			0.020 REF	-	

GENERIC **MARKING DIAGRAM***



XXXXX = Specific Device Code = Assembly Location А Υ = Year

WW = Work Week

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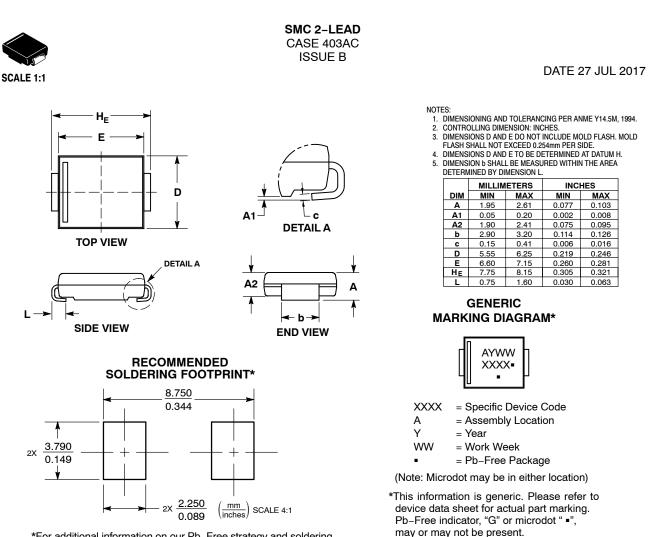
= Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " •", may or may not be present. Some products may not follow the Generic Marking.

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